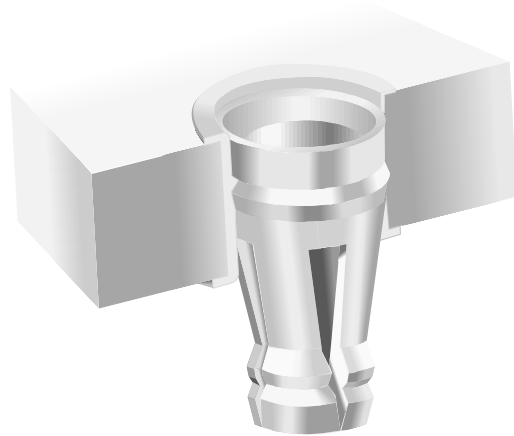


PHC Holtite® Series *Zero Profile Mylar® Carrier PGA Sockets*



D

FEATURES:

The PHC Series of Holtite® Zero Profile pin grid solderless sockets are designed to press fit into the plated through hole of a printed wiring board. This unique design allows the plated through hole to become the component socket. The elimination of soldering and insulator material gives the lowest mounting profile possible for the pin grid array and the maximum visibility to the circuit traces on the PCB for inspection and testing purposes.

- Low insertion and withdrawal force contacts available
- The profile of the printed wiring board with the Holtite® contact installed offers the lowest socketing profile, permitting card rack spacing as low as .400" (10,16)
- Precision machined, tapered entry, four-finger contact
- Retains minimum component lead lengths
- Maximum heat dissipation
- Removes artwork design restrictions
- Immediate conversion to the Holtite® system

MATERIAL SPECIFICATIONS:

Carrier Mylar®
 Contact Beryllium copper
 Plating Gold or tin/lead

PERFORMANCE SPECIFICATIONS:

MECHANICAL

Vibration Passed MIL-STD-202, Method 204, 20 G's
 Durability Passed MIL-STD-1344, Method 2016, 50 cycles
 Solderability Passed MIL-STD-202F, Method 208
 Insertion Force (5P) 92 Grams (3.2 oz.) average with .018" (0,46) dia. pol. steel pin and .043" (1,09) plated thru hole
 Withdrawal Force (5P) .. 103 Grams (3.6 oz.) average with .018" (0,46) dia. pol. steel pin and .043" (1,09) plated thru hole
 Contact Retention
 in Board 7.5 Lbs. per line average

ELECTRICAL

Contact Resistance 10 Milliohms
 Contact Rating 3 Amps

ENVIRONMENTAL

Humidity Passed MIL-STD-202, Method 106
 Thermal Shock Passed MIL-STD-202, Method 107, Cond. F
 Operation Temperature .. Gold inner contact -55°C to +125°C,
 Tin/lead inner contact -55°C to +105°C

Insertion Force (27P) 57 Grams (2.2 oz.) average with .018" (0,46) dia. pol. steel pin and a .039" (0,99) plated thru hole
 Withdrawal Force(27P) 30 Grams (1.1 oz.) average with .018" (0,46) dia. pol. steel pin and a .039" (0,99) plated thru hole

For performance specifications on 6P Holtites®, please consult factory

HOW TO ORDER

PHC - - H

Number of
Contacts

Plating Options

2 - Gold

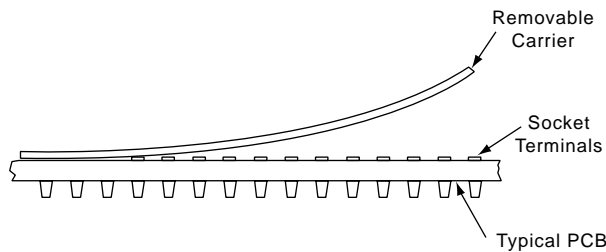
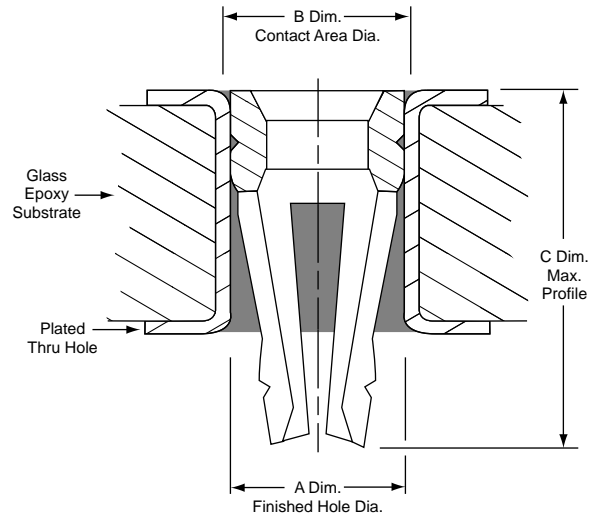
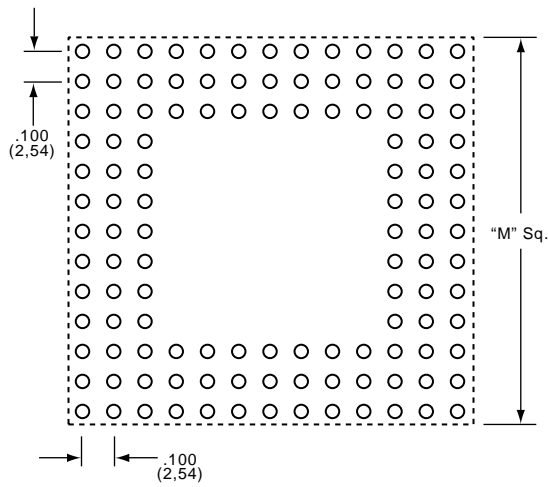
3 - Tin/Lead

Holtite
Selection
(Table 1)

Grid size

Footprint
Options
(Pg. D23)

Part Number Example:
PHC068-2E1333-H



DIMENSIONS

Mylar® Carrier Size	M ± .005**	Mylar® Carrier Size	M ± .005**
10 X 10	1.175	15 X 15	1.675
11 X 11	1.275	16 X 16	1.775
12 X 12	1.375	17 X 17	1.875
13 X 13	1.475	18 X 18	1.975
14 X 14	1.575		

* Non-Accumulative

TABLE 1 - HOLTITE® SELECTIONS

Option	Holtite®	Recommended Lead Size
E	5P	.016" - .021" Diameter
L	27P	Low force version of 5P .016" - .021" Diameter
F	6P	.020" - .030" Diameter

HOLTITE® PART NUMBERS / STANDARD CONFIGURATIONS

Holtite Part No.	Contact Material & Finish	Recommended Lead Size	Recommended Primary Drill Size	A Dim. Finished Plated-Thru Hole Size	B Dim. Contact Dia.	C Dim. Maximum Profile	Board Thickness	Plated-Thru Hole Finish
8134-HC-5P2 (Gold)	Beryllium Copper Gold-Plated	Rectangular Lead .011 x .018 ± .002 (0,28 x 0,46 ± 0,05) or Round Lead .016 - .021 (0,406 - 0,533) Diameter	.0453 (1,15)	.041 ± .002 (1,05 ± 0,05)	.044 ± .0005 (1,12 ± 0,01)	.100 (2,54)	.030 (0,75) Minimum	.0003 - .0005 (0,0076 - 0,0127) Electro-Deposited Tin/Lead Over .001 (0,0254) Min. Thick Electro Deposited Copper Plate
8134-HC-5P3 (Tin/Lead)	Beryllium Copper Tin/Lead Plated							
8134-HC-27P4 (Gold)	Beryllium Copper Gold-Plated							
8134-HC-27P3 (Tin/Lead)	Beryllium Copper Tin/Lead Plated							
8134-HC-6P2 (Gold)	Beryllium Copper Gold-Plated	Round Lead .020 - .030 (0,51 - 0,76) Diameter	.0635 (1,61)	.058 ± .002 (1,47 ± 0,05)	.0625 ± 0,0005 (1,59 ± 0,01)	.140 (3,56)		
8134-HC-6P3 (Tin/Lead)	Beryllium Copper Tin/Lead Plated							

Need more technical information?

Consult your Thomas & Betts sales office listed on the back cover